

MOSFET – Power, Single, N-Channel

40 V, 4.5 mΩ, 78 A

NTMFS5C460NL

Features

- Small Footprint (5x6 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V _{DSS}	40	V
Gate-to-Source Voltage	9		V _{GS}	±20	V
Continuous Drain	Steady State	T _C = 25°C	I _D	78	Α
Current R _{θJC} (Notes 1, 3)	State	T _C = 100°C		55	
Power Dissipation		T _C = 25°C	P _D	50	W
R _{θJC} (Note 1)		T _C = 100°C		25	
Continuous Drain	Steady State	T _A = 25°C	I _D	21	Α
Current R _{θJA} (Notes 1, 2, 3)	State	T _A = 100°C		15	
Power Dissipation		T _A = 25°C	P_{D}	3.6	W
R _{θJA} (Notes 1 & 2)		T _A = 100°C		1.8	
Pulsed Drain Current	$T_A = 25^{\circ}C, t_p = 10 \mu s$		I _{DM}	520	Α
Operating Junction and Storage Temperature			T _J , T _{stg}	-55 to +175	°C
Source Current (Body Diode)			Is	56	Α
Single Pulse Drain-to-Source Avalanche Energy (I _{L(pk)} = 5 A)			E _{AS}	107	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

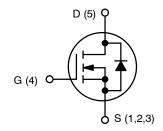
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

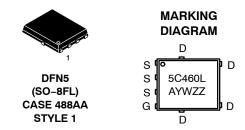
Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	$R_{\theta JC}$	3.0	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	42	

- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.
- 3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
40 V	4.5 mΩ @ 10 V	78 A
	7.2 mΩ @ 4.5 V	



N-CHANNEL MOSFET



5C460L = Specific Device Code A = Assembly Location

Y = Year
W = Work Week
ZZ = Lot Traceability

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit	
OFF CHARACTERISTICS		L						
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 250 μA		40	_	_	V	
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /	GO / D		-	21	-	mV/°C	
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V,	T _J = 25 °C	-	-	10	μΑ	
		V _{DS} = 40 V	T _J = 125°C	-	-	250		
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS}	= 20 V	-	-	100	nA	
ON CHARACTERISTICS (Note 4)						•		
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D =$	= 40 μΑ	1.2	-	2.0	V	
Threshold Temperature Coefficient	V _{GS(TH)} /T _J			-	-5.1	-	mV/°C	
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 35 A	-	3.7	4.5	mΩ	
		V _{GS} = 4.5 V	I _D = 35 A	-	5.8	7.2	†	
Forward Transconductance	g _{FS}	V _{DS} = 15 V, I _D	= 35 A	-	72	_	S	
CHARGES, CAPACITANCES & GATE RESIS	TANCE					1		
Input Capacitance	C _{ISS}	$V_{GS} = 0 \text{ V, f} = 1 \text{ MHz, V}_{DS} = 20 \text{ V}$		-	1300	_	pF	
Output Capacitance	C _{OSS}			-	530	_	1	
Reverse Transfer Capacitance	C _{RSS}			-	22	_	1	
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 20 V; I _D = 35 A		-	23	-	nC	
Total Gate Charge	Q _{G(TOT)}	$V_{GS} = 4.5 \text{ V}, V_{DS} = 20 \text{ V}; I_D = 35 \text{ A}$		-	11	-	nC	
Threshold Gate Charge	Q _{G(TH)}			-	2.5	-		
Gate-to-Source Charge	Q _{GS}			-	4.7	-		
Gate-to-Drain Charge	Q_{GD}			-	3.0	_	1	
Plateau Voltage	V_{GP}			-	3.3	-	V	
SWITCHING CHARACTERISTICS (Note 5)	<u>. I </u>					ı	1	
Turn-On Delay Time	t _{d(ON)}	V_{GS} = 4.5 V, V_{DS} = 20 V, I_{D} = 35 A, R_{G} = 1.0 Ω		-	9.2	-	ns	
Rise Time	t _r			-	3.4	_	1	
Turn-Off Delay Time	t _{d(OFF)}			-	17	-	1	
Fall Time	t _f			-	4.4	_	1	
DRAIN-SOURCE DIODE CHARACTERISTIC	s				•			
Forward Diode Voltage	V_{SD}	V _{GS} = 0 V,	T _J = 25°C	-	0.86	1.2	V	
		I _S = 35 A	T _J = 125°C	-	0.75	_	1	
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 \text{ V, dIs/dt} = 100 \text{ A/}\mu\text{s,}$ $I_{S} = 35 \text{ A}$		-	29	_	ns	
Observe Trees	t _a			-	14	_	1	
Charge Time	u							
Discharge Time	t _b			-	14	_	1	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.

5. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

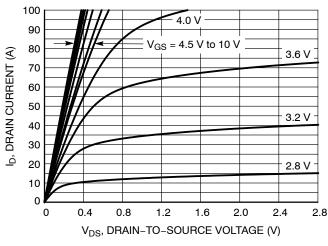


Figure 1. On-Region Characteristics

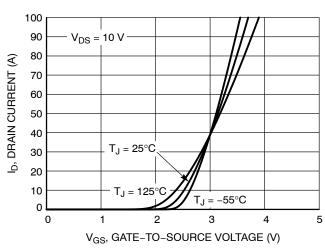


Figure 2. Transfer Characteristics

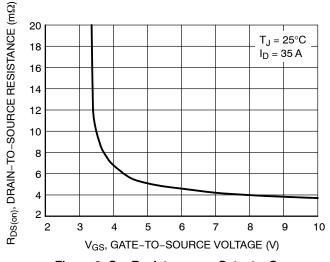


Figure 3. On-Resistance vs. Gate-to-Source Voltage

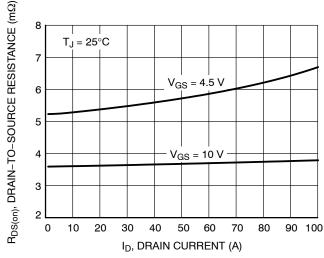


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

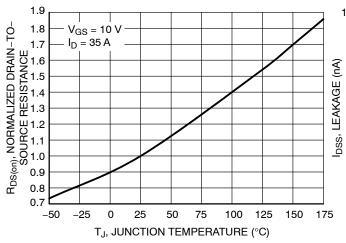


Figure 5. On–Resistance Variation with Temperature

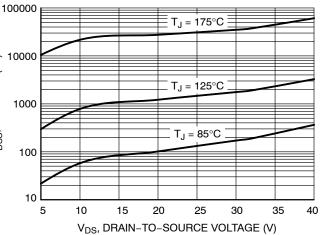


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

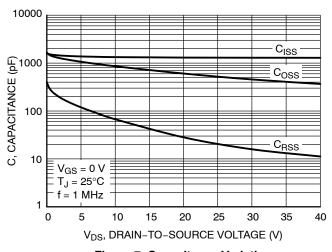


Figure 7. Capacitance Variation

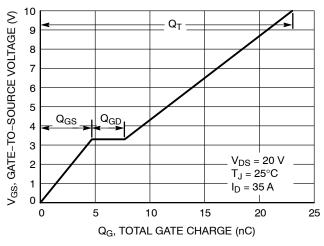


Figure 8. Gate-to-Source vs. Total Charge

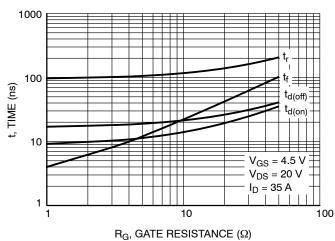


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

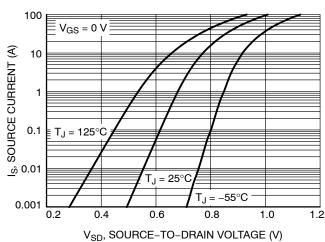


Figure 10. Diode Forward Voltage vs. Current

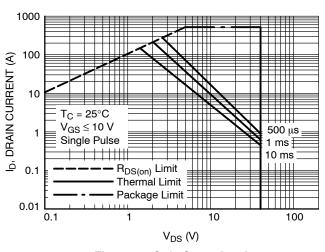


Figure 11. Safe Operating Area

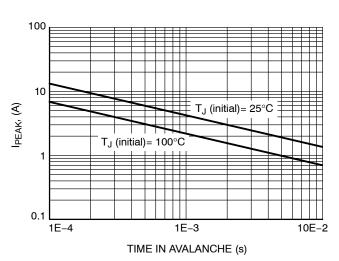
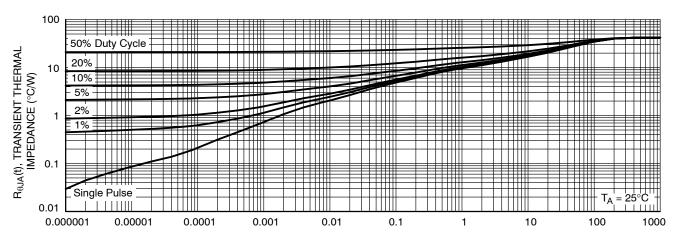


Figure 12. I_{PEAK} vs. Time in Avalanche

TYPICAL CHARACTERISTICS



t, RECTANGULAR PULSE DURATION (s)

Figure 13. Thermal Response

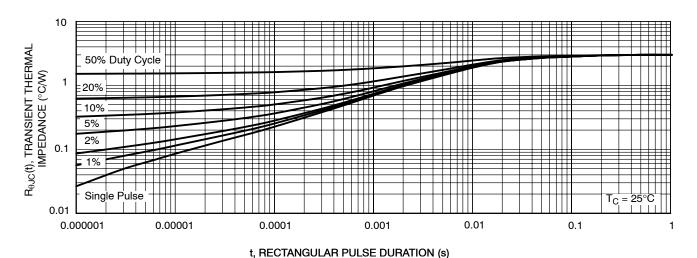


Figure 14. Thermal Response

DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NTMFS5C460NLT1G	5C460L	DFN5 (Pb-Free)	1500 / Tape & Reel
NTMFS5C460NLT3G	5C460L	DFN5 (Pb-Free)	5000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.





DFN5 5x6, 1.27P (SO-8FL) CASE 488AA ISSUE N

DATE 25 JUN 2018

NOTES:

- DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETER. DIMENSION D1 AND E1 DO NOT INCLUDE
- MOLD FLASH PROTRUSIONS OR GATE BURRS

	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	0.90	1.00	1.10		
A1	0.00	-	0.05		
b	0.33	0.41	0.51		
С	0.23	0.28	0.33		
D	5.00	5.15	5.30		
D1	4.70	4.90	5.10		
D2	3.80	4.00	4.20		
E	6.00	6.15	6.30		
E1	5.70	5.90	6.10		
E2	3.45	3.65	3.85		
е		1.27 BSC			
G	0.51	0.575	0.71		
K	1.20	1.35	1.50		
L	0.51	0.575	0.71		
L1	0.125 REF				
M	3.00	3.40	3.80		
θ	0 °		12 °		

GENERIC MARKING DIAGRAM*

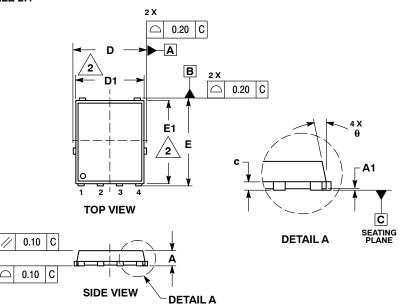


XXXXXX = Specific Device Code

= Assembly Location Α

Υ = Year W = Work Week ZZ = Lot Traceability

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present. Some products may not follow the Generic Marking.





*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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